LEOCO CORPORATION | PRODUCTION SPECIFICATION | No. | S-18-5083 REV

* 5083 Series Connector System

This product specification contains the test method, the following datum are the general performance and requirements of the LEOCO 5083 series connector

1. Construction and dimensions shall be in accordance with the referenced drawings. 产品结构和尺寸依据所提供的产品图面.

2. Characteristics 特性:

Current rating 额定电流: 7A AC,DC Voltage rating 额定电压: 250V AC,DC Temperature rating 额定温度: -25℃ ~ +105℃

Applicable wire 适用线材: conductor construction size #18 ~ #26

3. Electrical performance 电气特性:									
ITEM	DESCRIPTION	TEST METHOD & CONDITION	REQUIREMENT						
	内容	测试方法与条件	需求						
3-1	Contact Resistance	It should be tested in accordance with	20 m $Ω$ max.						
	接触阻抗	method EIA-364-23							
3-2	Insulation	It should be tested in accordance with	1000M Ω min.						
	Resistance	Method EIA-364-21							
	绝缘阻抗								
3-3	Dielectric	Unmated connectors shall be tested in	No breakdown						
	Withstanding	Accordance with method EIA-364-20							
	Voltage	When the AC 1000 V rms for one minute							
	耐电压	applied between adjacent contacts.							
4. Mechanical Performance 机械特性:									
ITEM	DESCRIPTION	TEST METHOD & CONDITION	REQUIREMENT						
	内容	测试方法与条件	需 求						
4-1	Crimp	Pulling load shall be applied between	AWG #18: 10.0 kgf min.						
	Tensile	Correctly crimped contact and wire at a	AWG #20: 6.0 kgf min.						
	Strength	constant speed. Pulling speed: 25 mm /	AWG #22: 4.0 kgf min.						
	铆合张力强度	minute.	AWG #24: 2.5 kgf min.						

ITEM	DESCRIPTION	TEST METHOD & CONDITION	REQUIREMENT		
	内容	测试方法与条件	需求		
4-1	Crimp Tensile Strength 铆合张力强度	Pulling load shall be applied between Correctly crimped contact and wire at a constant speed. Pulling speed: 25 mm / minute.	AWG #18: 10.0 kgf min. AWG #20: 6.0 kgf min. AWG #22: 4.0 kgf min. AWG #24: 2.5 kgf min. AWG #26: 1.5 kgf min.		
4-2	Contact Insertion Force 接触插入力	The force required to insert a contact into a housing. Inserting speed: 25 mm / minute.	1.8 kgf max.		
4-3	Contact removal Force 接触拨出力	Crimped contact mounted in a housing shall be pulled in an alignment at a constant speed of 25 mm / minute.	3.6 Kgf min.		
4-4	Post retention force 保持力	The end of a post shall be pushed in a perpendicular to base housing at a constant speed of 25mm/minute			
4-5	Insertion Force 插入力	Housing with contact mating header at a constant speed of 25 mm / minute.	1.2 kgf min		
4-6	Withdrawal Force 拨出力	Housing with contact mating header, Pull out from header at speed 25 mm / minute.	0.35 kgf max		
4-7	Durability 耐久力	It should be tested in accordance with method EIA-364-09	No defects. Contact resistance shall be		

Connector shall be subjected to 200

cycles of insertion and withdrawal

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 $20m\Omega$ max

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ITEM	DESCRIPTION 内容	TEST METHOD & CONDITION 测试方法与条件		REQUIREMENT 需 求		
4-8	Vibration 振动性	The connector mated PCB shall be vibrated in accordance with method EIA-364-28. There shall be no current discontinuity longer than 1 microsecond during the te Frequency: 10-55-10 Hz / min. Amplitude: 1.52mm Period: 2 hours for each direction	ir d C	No evidence of loosening of parts or electric discontinuity. Contact resistance less than twice of initial.		
5. Envir	onmental Performanc	e 环境特性:				
ITEM	DESCRIPTION 内容	TEST METHOD & CONDITION 测试方法与条件		REQUIREM 需	/IENT 找	
5-1	Humidity 耐湿性	The unmated connector shall be tested accordance with method EIA-364-31. Temperature: 40±2 °C Humidity: 90 ~ 95 % (RH) Period: 96 hours.	T Ir to	IO damage. Contact resistar Than twice of in Insulation resist To paragraph 3-2 Tielectric withst To parage: to para	itial. ance: 2. and in	g
5-2	Salt Spray 盐雾试验	Connector shall be tested in accordance with method EIA-364-26 Temperature: 35±2 °C Density: 5 % in weight. Period: 24 hours.	C	IO damage. Contact resistar nan twice of ini		Ś
5-3	Solderability 着锡性	Connector termination ends shall be checked for solderability in accordance with method EIA-364-252 Solder temperature: 245±5 °C Immersion period: 5±0.5 sec.	N	IO damage. /linimum: 95 % nmersed area.	of	
5-4	Resistance to Soldering Heat 附着耐热性	Specimen shall be mounted on PCB. Solder temperature: 255±5 °C Immersion period: 5±0.5 sec.		IO damage and eformation.	t	
5-5	Temperature rise 温升	Mate connectors: Measure the temperarise at rated current after 4 hours. Test method: EIA-364-70		emperature ris	e 30°0	<u> </u>
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